

Title (en)
Electroplating apparatus

Title (de)
Galvanisiereinrichtung

Title (fr)
Appareil pour le revêtement électrolytique

Publication
EP 1717352 A2 20061102 (EN)

Application
EP 06005414 A 20060316

Priority
JP 2005125538 A 20050422

Abstract (en)
An electroplating apparatus is provided which includes a solution tank which has at least a bottom plate and a side plate and inside which electroplating solution is poured and a cathode plate and an anode plate which are horizontally placed so as to face each other in the electroplating solution in the solution tank, in which one plate of the cathode plate and the anode plate is an object to be electroplated and placed in a lower position than the other plate, in which an opening through which the cathode plate and the anode plate are inserted into the solution tank is provided in the side plate of the solution tank, and in which a shield plate which is detachable shields the opening of the solution tank.

IPC 8 full level
C25D 7/12 (2006.01); **C25D 17/00** (2006.01)

CPC (source: EP KR US)
C25D 7/123 (2013.01 - EP US); **C25D 17/001** (2013.01 - EP US); **C25D 17/008** (2013.01 - EP US); **C25D 17/06** (2013.01 - KR); **C25D 17/10** (2013.01 - KR); **C25D 17/12** (2013.01 - KR)

Citation (applicant)
JP 2003301299 A 20031024 - YAMAMOTO MEKKI SHIKENKI KK

Cited by
WO2010086111A3

Designated contracting state (EPC)
AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IS IT LI LT LU LV MC NL PL PT RO SE SI SK TR

Designated extension state (EPC)
AL BA HR MK YU

DOCDB simple family (publication)
EP 1717352 A2 20061102; **EP 1717352 A3 20070117**; CN 1865519 A 20061122; CN 1865519 B 20100811; JP 2006299367 A 20061102; KR 20060111385 A 20061027; TW 200637935 A 20061101; US 2006237304 A1 20061026

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EP 06005414 A 20060316; CN 200610074516 A 20060421; JP 2005125538 A 20050422; KR 20060035497 A 20060419; TW 95108977 A 20060316; US 37741506 A 20060317